

Specifications

Insulation Resistance: 1,000MΩ min. at 500V DC
 Dielectric Withstanding Voltage: 700V AC for 1 minute
 Contact Resistance: 30mΩ max. at 10mA/20mV max.
 Operating Temperature Range: -55°C to +170°C
 Contact Force: 30g min. per pin at minimum displacement of 0.45mm
 90g max. per pin at maximum displacement of 0.8mm

Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
 Contacts: Beryllium Copper (BeCu)
 Plating: Gold over Nickel



Part Number (Details)

NP178 - 644 01 - * - **

Series No.

No. of Contact Pins

Design Number

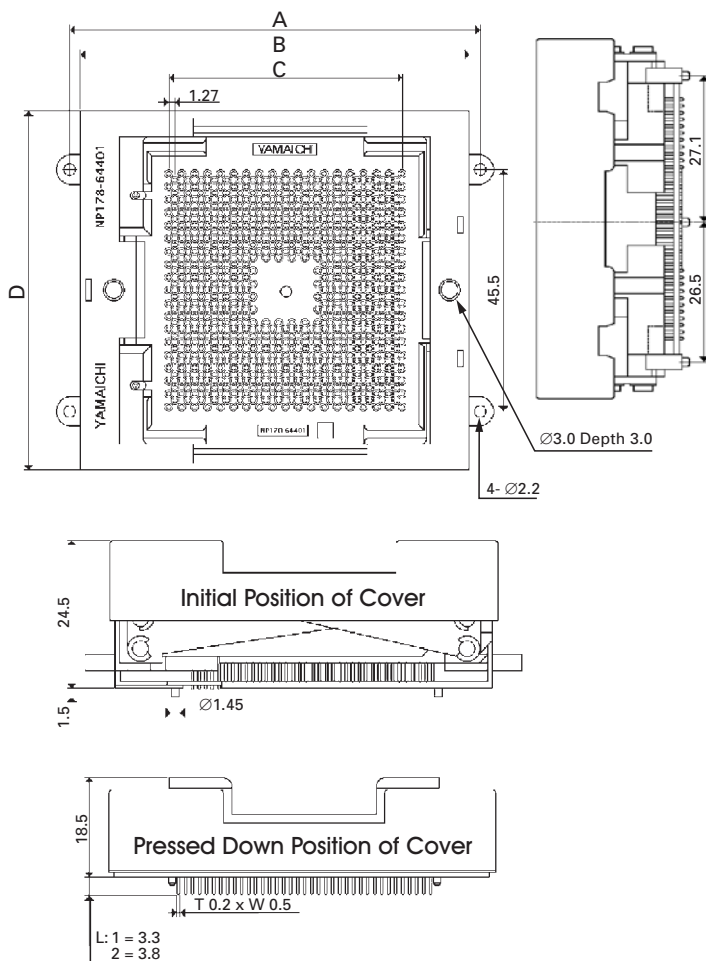
Matching IC Diameter /Socket Pin Length

1: ∅0.35±0.05 1: L = 3.3
 2: ∅0.45±0.05 2: L = 3.8

MF = Flanged

Unmarked = Not Flanged

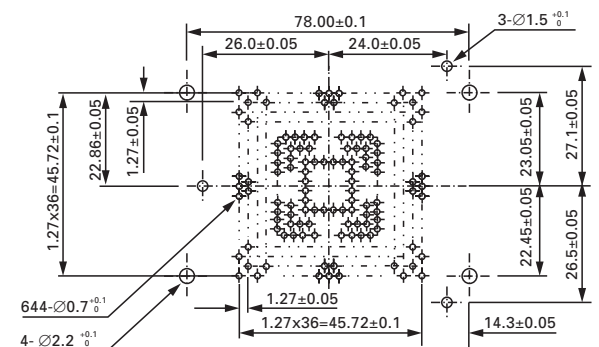
Outline Socket Dimensions



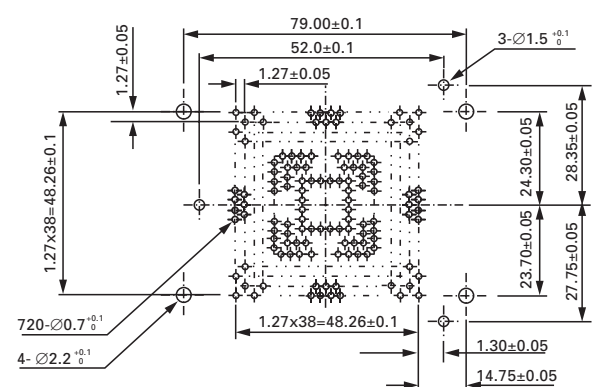
Recommended PC Board Layout

Top View from Socket

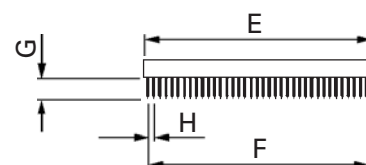
NP178-64401-**-**



NP178-72002-**-**



Outline IC Dimensions



Part Number	Grid Size	Pin Count	Socket Dimensions				IC Dimensions			
			A	B	C	D	E max.	F	G	H
NP178-64401-**-**	19 x 19	644	78.0	74.0	1.27x36=45.72	67.0	□50.0	45.72	2.54~5.9	1.27
NP178-72002-**-**	20 x 20	720	79.0	75.0	1.27x38=48.26	69.5	□52.8	48.26	2.54~5.9	1.27